

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Tokuo SHIMIZU	07/20/2006
Tetsunori YANO	07/20/2006
RECEIVING PARTY DATA	
Name:	Hitachi Plant Technologies, Ltd.
Street Address:	1-14, Uchi-Kanda 1-chome, Chiyoda-ku
City:	Tokyo
State/Country:	JAPAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11463184
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NAME OF SUBMITTER:	David S. Safran
Total Attachments: 1 source=Assignment_740107_197#page1.tif	

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PATENT
REEL: 018073 FRAME: 0472

ASSIGNMENT

For good and valuable consideration, the sufficiency and receipt of which is hereby acknowledged, as a below named inventor, I hereby sell and assign to Hitachi Plant Technologies, Ltd.
of 1-14, Uchi-Kanda 1-chome, Chiyoda-ku, Tokyo, Japan
its successors and assigns or other legal representatives all my rights, title and interest, in and for the United States of America, in and to

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invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefore, filed on even date herewith and all United States Letters Patent which may be granted therefore, and all divisions, continuations, reissues, reexaminations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi Plant Technologies, Ltd., its successors, assigns or other legal representatives, to the full end of the term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi Plant Technologies, Ltd.

- | | (Full Name) | (Signature) |
|--|---------------------------------|-----------------------|
| 1. Date: <u>July 20, 2006</u> | Inventor: <u>Tokuo SHIMIZU</u> | <u>Tokuo Shimizu</u> |
| Residence: <u>Same as Post Office Address</u> | Citizen of: <u>Japan</u> | |
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| 2. Date: <u>July 20, 2006</u> | Inventor: <u>Tetsunori YANO</u> | <u>Tetsunori Yano</u> |
| Residence: <u>Same as Post Office Address</u> | Citizen of: <u>Japan</u> | |
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| 3. Date: _____ | Inventor: _____ | |
| Residence: <u>Same as Post Office Address</u> | Citizen of: _____ | |
| Post Office Address: _____ | | |
| 4. Date: _____ | Inventor: _____ | |
| Residence: <u>Same as Post Office Address</u> | Citizen of: _____ | |
| Post Office Address: _____ | | |